

# SOT932-1

plastic thin fine-pitch ball grid array package; 176 balls; body  
6 x 15 x 0.7 mm

8 February 2016

Package information

## 1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA176
Package type industry code	TFBGA176
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-246
Mounting method type	S (surface mount)
Issue date	16-1-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		14.9	-	15	15.1	mm
E	package width		5.9	-	6	6.1	mm
A	seated height		[tbd]	-	1.15	1.15	mm
A <sub>2</sub>	package height		0.65	-	0.7	0.8	mm
n <sub>2</sub>	actual quantity of termination		-	-	176	-	



2. Package outline

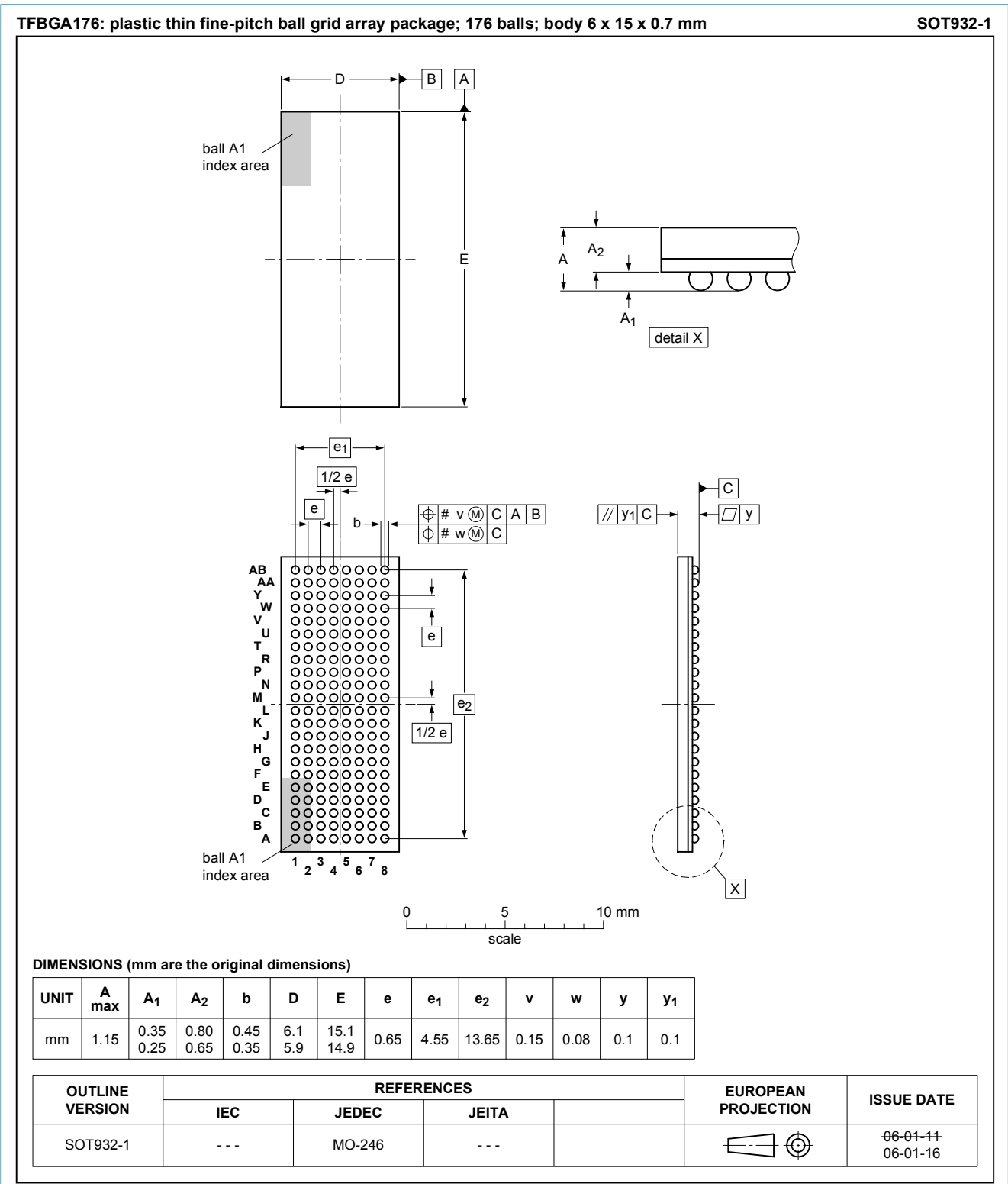


Fig. 1. Package outline TFBGA176 (SOT932-1)

3. Soldering

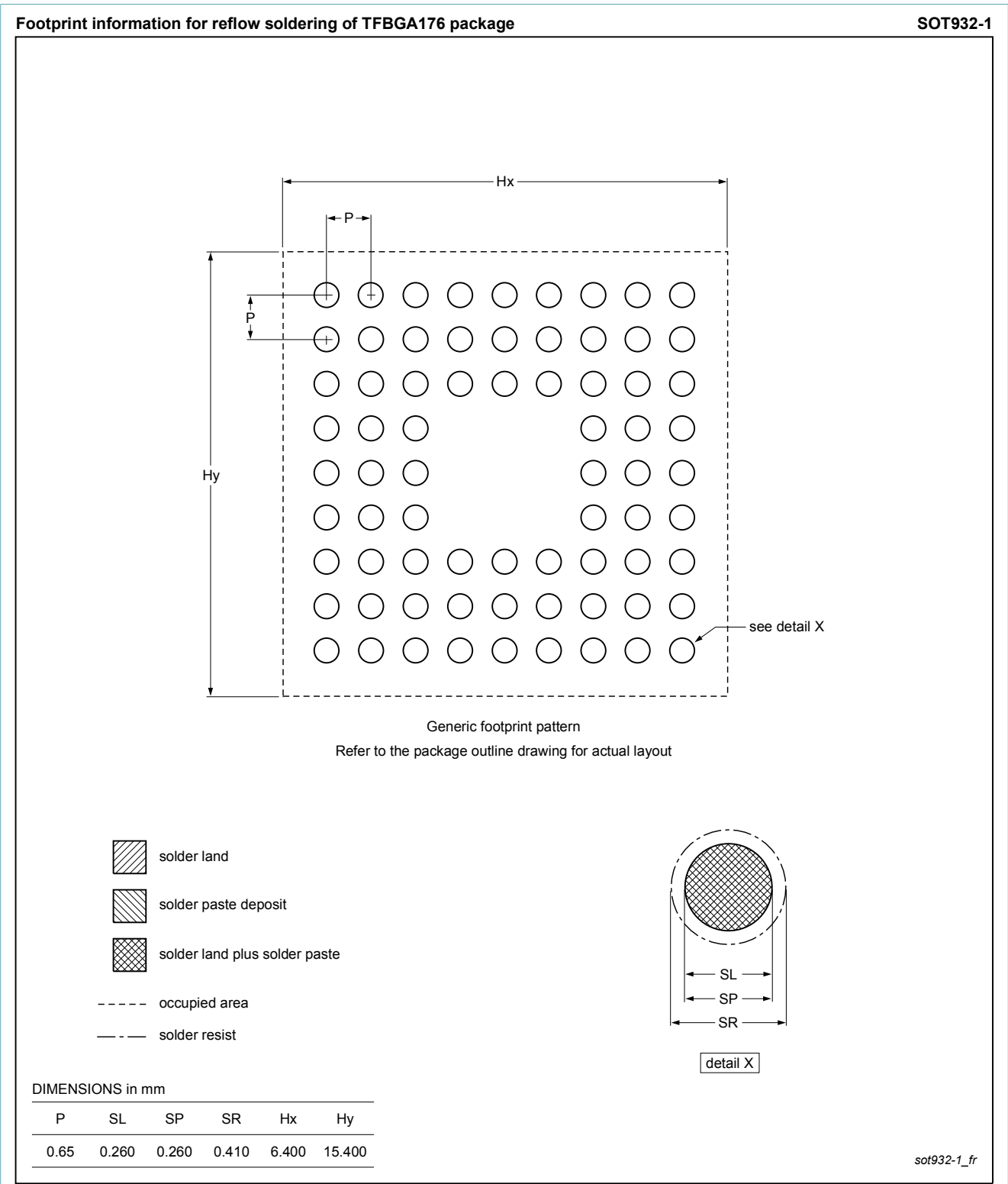


Fig. 2. Reflow soldering footprint for TFBGA176 (SOT932-1)

## 4. Legal information

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